L Number	Hits	Search Text	DB	Time stamp
1	0	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6	USPAT;	2003/08/12 13:00
		(film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4	US-PGPUB;	
		plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	ЕРО; ЛРО;	
		same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2	DERWENT;	
ļ		surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4	IBM_TDB	
		remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4	_	
		estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4		
İ		(forc\$4 load\$4 strain\$4 stress\$4))) and "180.degree. C." and		
		((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4		
İ		bind\$4 deposit\$4 set\$4 cur\$4))		
2	0	"180.degree. C." same ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 12:58
[(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
3	0	"180.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 12:59
·	ŭ	(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	2005/00/12 12:57
		(whherea whista, have a current anhance, north anthal))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	0	"180.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 12:59
7	U	(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	2003/00/12 12.39
		(appriso apprysor pater orition depositor setter enter)	ЕРО; ЛРО;	
			DERWENT;	
_	0	" d	IBM_TDB	2002/09/12 12:50
5	0	".degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5	USPAT;	2003/08/12 12:59
Ì		apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
	10010	1 00 100 1 04 1 0 04 1 0 04 1 0 06	IBM_TDB	2002/00/12 14 40
6	10018	degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5	USPAT;	2003/08/12 14:48
		apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
_			IBM_TDB	2002/00/12 14 47
7	74	(degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5	USPAT;	2003/08/12 14:47
		apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4	US-PGPUB;	
		adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate	ЕРО; ЈРО;	
		specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) same	DERWENT;	
		((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base	IBM_TDB	
		support\$4)))		0000000000
8	51	((degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5	USPAT;	2003/08/12 14:55
		apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4	US-PGPUB;	
		adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate	ЕРО; ЈРО;	
		specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) same	DERWENT;	
		((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base	IBM_TDB	
		support\$4)))) and ((metal\$4 nickel alum\$4 iron silver gold copper)		
		near4 (film layer plate sheet board))		
10	8887	(degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 14:49
		(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT,	
			IBM TDB	
9	35	(degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5	USPAT;	2003/08/12 14:51
•	33	apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4	US-PGPUB;	
		adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate	EPO; JPO;	
		specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near5	DERWENT;	
		(hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4))	IBM_TDB	1

12	24	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4	USPAT; US-PGPUB;	2003/08/12 15:04
		fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film	ЕРО; ЛРО;	
		substrate specimen cable wire)) same ((polymer\$4 elastomer\$4	DERWENT;	
		plastic\$4) near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4	IBM_TDB	
		cur\$4))		
14	2576	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 14:57
		(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((metal\$4	US-PGPUB;	
		nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet	ЕРО; ЈРО;	
		board))	DERWENT;	
	•		IBM_TDB	
15	2576	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 14:57
		(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((metal\$4	US-PGPUB;	
		nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet	ЕРО; ЛРО;	
		board))	DERWENT;	
		Journ J	IBM TDB	
16	6	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4	USPAT;	2003/08/12 15:07
10	١	(appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4	US-PGPUB;	2003/06/12 13.07
		fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film	ЕРО; ЛРО;	
		substrate specimen cable wire)) and ((polymer\$4 elastomer\$4 plastic\$4)	DERWENT;	
		near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4) near6	IBM_TDB	
		((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate		
		sheet board)))		
17	4	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6	USPAT;	2003/08/12 15:07
		(film substrate specimen cable wire)) same (polymer\$4 near5 (hot	US-PGPUB;	
		heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4) near6 ((metal\$4	ЕРО; ЛРО;	
		nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet	DERWENT;	
		board)))	IBM_TDB	
-	213	73/827.ccls.	USPAT;	2003/08/08 15:16
		•	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
_	123	73/834.ccls.	USPAT;	2003/08/08 15:16
		13/33 1144131	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
		•	IBM TDB	
	47	73/835.ccls.	USPAT;	2003/08/08 15:16
-	1 4'	737833.0018.	US-PGPUB;	2003/00/00 13.10
	}		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	2002	((convert fived adhored handed inimed alved -4:-1-04 -441-04)		2003/08/08 15:40
-	2993	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6	USPAT;	2003/06/08 13:40
		(film substrate specimen cable wire) near4 (metal\$4 plate)) same	US-PGPUB;	
		(polymer\$4 plastic\$4) same (hot heat\$4 warm\$4 temperature)	ЕРО; ЛРО;	
	1		DERWENT;	
			IBM_TDB	0000/00/05 15
-	35	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6	USPAT;	2003/08/08 15:45
		(film substrate specimen cable wire) near4 (metal\$4 plate)) same	US-PGPUB;	
		(polymer\$4 plastic\$4) same (hot heat\$4 warm\$4 temperature)) and	ЕРО; ЈРО;	
		((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 stretch\$4 draw\$4) near6	DERWENT;	
		(measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4) near4	IBM_TDB	
	1	(forc\$4 load\$4 strain\$4 stress\$4))		
-	310	1.	USPAT;	2003/08/08 15:46
		(film substrate specimen cable wire) near4 (metal\$4 plate)) same	US-PGPUB;	
		((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4	ЕРО; ЛРО;	
		deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)	DERWENT;	
		appoint to the title to the tit	IBM_TDB	
	L		ממו_וייותי	l

-	9	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4	USPAT; US-PGPUB; EPO; JPO;	2003/08/11 10:36
		deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)	DERWENT; IBM_TDB	
-	7	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 plate)) same	USPAT; US-PGPUB;	2003/08/08 15:55
		((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6	EPO; JPO; DERWENT; IBM TDB	
		(measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	_	
-	75	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) and (((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/08 15:59
-	0	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) and (((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:58
-	2548	(measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)) 73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4	USPAT;	2003/08/08 15:59
		stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	
-	2	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire) near4 ((metal\$4 conductive) near4 (sheet layer board plate) near6 (hot heat\$4 warm\$4))	USPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB	2003/08/08 17:11
-	2	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 bind\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire) near4 ((metal\$4 conductive) near4 (sheet layer board plate) near6 (hot heat\$4 warm\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:14
-	38	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 bind\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire sheet layer board plate) near6 (hot heat\$4 warm\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:15
_	2	("5641913" "5969262").PN.	USPAT	2003/08/08 17:16
-	137	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/11 11:09
-	1	(platform plate\$2 surface base support\$4)) (((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 12:39
		(measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))		

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-	37	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 13:21
		remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	IDIVI_TUD	
-	2	6455152.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/11 12:46
-	65	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 16:13
		remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))		
-	81	(((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:08
-	11	monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)) (((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/11 17:13
		near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	IBM_TDB	
-	26	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 detach\$4 stretch\$4 sens\$4 monitor\$4 bond\$4) near4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:47
-	0	(forc\$4 load\$4 strain\$4 stress\$4)) ((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:48
-	0	(forc\$4 load\$4 strain\$4 stress\$4))) and "180.degree. C." ((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/12 12:55
		surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and "177.degree. C." and	IBM_TDB	
		((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))		

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